

**STRUCTURE TO ACHIEVE HIGH-Q AND LOW INSERTION LOSS
FILM BULK ACOUSTIC RESONATORS**

Abstract of the Disclosure

5

- A film bulk acoustic resonator is formed on a substrate. The film bulk acoustic resonator includes a layer of piezoelectric material having a first surface proximate the substrate, and a second surface distal from the substrate. The first conductive layer deposited on the first surface of the piezoelectric material
- 10 includes a first portion having a surface on a different plane than a surface associated with a second portion.

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